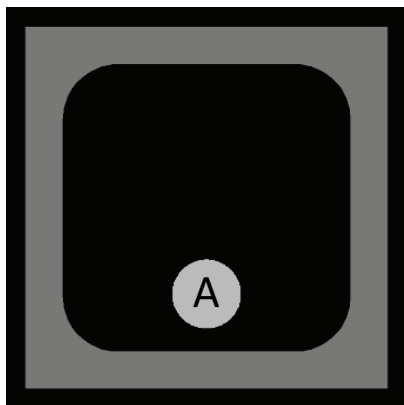


Silicon PIN Photodiode



DESCRIPTION

T330P6 chip is a PIN photodiode with 0.23 mm² sensitive area, high speed and high photo sensitivity. It is sensitive to the visible and near infrared light spectrum with a peak sensitivity at 900 nm. Anode is the bond pad on top, cathode is the backside contact.

GENERAL INFORMATION

The datasheet is based on Vishay optoelectronics sample testing under certain predetermined and assumed conditions, and is provided for illustration purpose only. Customers are encouraged to perform testing in actual proposed packaged and used conditions. Vishay optoelectronics die products are tested using Vishay optoelectronics based quality assurance procedures and are manufactured using Vishay optoelectronics established processes. Estimates such as those described and set forth in this datasheet for semiconductor die will vary depending on a number of packaging, handling, use, and other factors. Therefore sold die may not perform on an equivalent basis to standard package products.

FEATURES

- Package type: chip
- Package form: single chip
- Dimensions (L x W x H in mm): 0.67 x 0.67 x 0.28
- Wafer diameter (in mm): 150
- Sensitive area (in mm²): 0.23
- Peak sensitivity wavelength: 900 nm
- High photo sensitivity
- High sensitivity
- Suitable for visible light and near infrared radiation
- Fast response times
- Angle of half sensitivity: $\phi = \pm 60^\circ$
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912



APPLICATIONS

- High speed photo detector

PRODUCT SUMMARY

COMPONENT	I_{ra} (μA)	ϕ (°)	$\lambda_{0.5}$ (nm)
T330P6	1.95	± 60	580 to 1040

Note

- Test conditions see table "Basic Characteristics"

ORDERING INFORMATION

ORDERING CODE	PACKAGING	REMARKS	PACKAGE FORM
T330P6-SD-F	Wafer sawn on foil with disco frame	MOQ: 150 000 pcs	Chip

Note

- MOQ: minimum order quantity

ABSOLUTE MAXIMUM RATINGS ($T_{amb} = 25^\circ\text{C}$, unless otherwise specified)

PARAMETER	TEST CONDITION	SYMBOL	VALUE	UNIT
Reverse voltage		V_R	60	V
Junction temperature		T_j	100	°C
Operating temperature range		T_{amb}	-40 to +100	°C
Storage temperature range		T_{stg1}	-40 to +100	°C
Storage temperature range on foil		T_{stg2}	-40 to +50	°C

BASIC CHARACTERISTICS ($T_{amb} = 25\text{ }^{\circ}\text{C}$, unless otherwise specified)						
PARAMETER	TEST CONDITION	SYMBOL	MIN.	TYP.	MAX.	UNIT
Breakdown voltage	$I_R = 100\text{ }\mu\text{A}$, $E = 0$	$V_{(BR)}$	60	-	-	V
Reverse dark current	$V_R = 10\text{ V}$, $E = 0$	I_{ro}	-	< 1	3	nA
Diode capacitance	$V_R = 0\text{ V}$, $f = 1\text{ MHz}$, $E = 0$	C_D	-	3.5	-	pF
	$V_R = 3\text{ V}$, $f = 1\text{ MHz}$, $E = 0$	C_D	-	1.7	-	pF
Reverse light current	$E_e = 1\text{ mW/cm}^2$, $\lambda = 890\text{ nm}$, $V_R = 5\text{ V}$	I_{ra}	-	1.98	-	μA
	$E_e = 1\text{ mW/cm}^2$, $\lambda = 950\text{ nm}$, $V_R = 5\text{ V}$	I_{ra}	-	1.95	-	μA
Angle of half sensitivity		ϕ	-	± 60	-	$^{\circ}$
Wavelength of peak sensitivity		λ_p	-	900	-	nm
Range of spectral bandwidth		$\lambda_{0.5}$	-	580 to 1040	-	nm
Rise time	$V_R = 5\text{ V}$, $R_L = 1\text{ k}\Omega$, $\lambda = 830\text{ nm}$	t_r	-	210	-	ns
	$V_R = 5\text{ V}$, $R_L = 50\text{ }\Omega$, $\lambda = 950\text{ nm}$	t_r	-	2750	-	ns
Fall time	$V_R = 5\text{ V}$, $R_L = 1\text{ k}\Omega$, $\lambda = 830\text{ nm}$	t_f	-	230	-	ns
	$V_R = 5\text{ V}$, $R_L = 50\text{ }\Omega$, $\lambda = 950\text{ nm}$	t_f	-	2300	-	ns

Note

- The measurements are based on samples of die which are mounted on a TO-header without resin coating

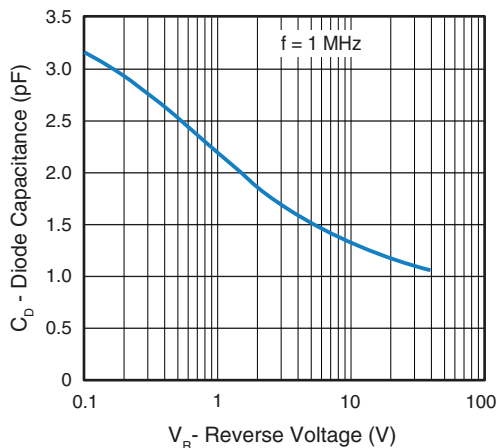
BASIC CHARACTERISTICS ($T_{amb} = 25\text{ }^{\circ}\text{C}$, unless otherwise specified)


Fig. 1 - Diode Capacitance vs. Reverse Voltage

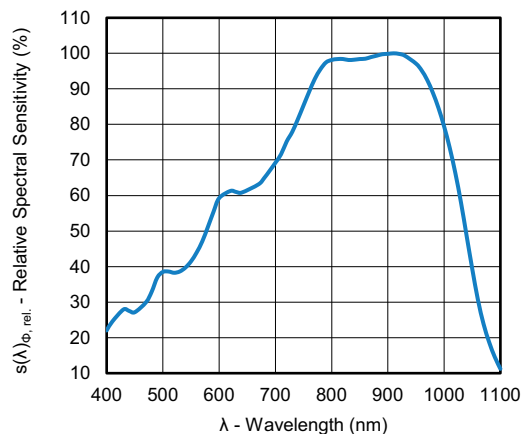


Fig. 2 - Relative Spectral Sensitivity vs. Wavelength

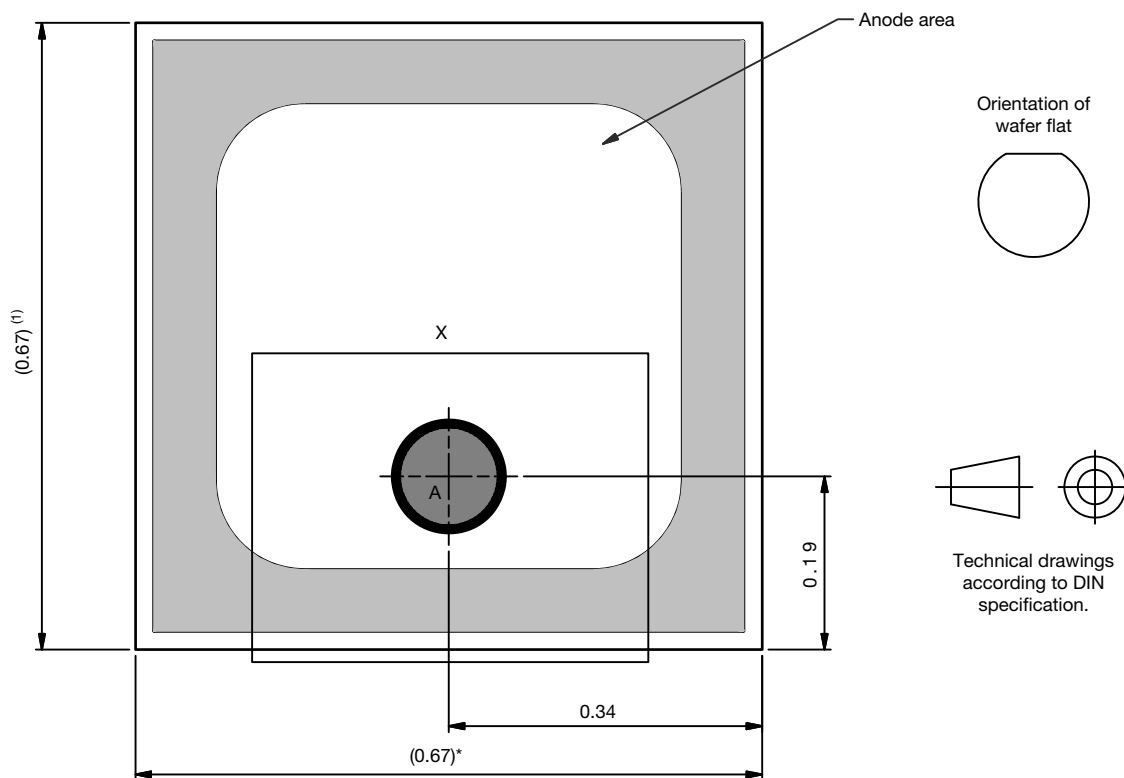
MECHANICAL DIMENSIONS					
PARAMETER	SYMBOL	MIN.	TYP.	MAX.	UNIT
Length of chip edge (x-direction)	L_x		0.67		mm
Length of chip edge (y-direction)	L_y		0.67		mm
Sensitive area	A_S		0.23		mm^2
Wafer diameter	D		150		mm
Die height	H	0.265	0.28	0.295	mm
Bond pad anode	$x * y$		0.1 x 0.1		mm^2

ADDITIONAL INFORMATION

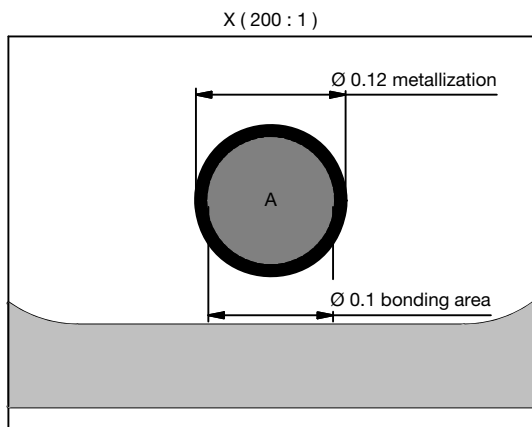
Frontside metallization, anode	Al
Backside metallization, cathode	NiV-Ag
Dicing	Sawing
Die bonding technology	Epoxy bonding

Note

- All chips are checked in accordance with the Vishay Semiconductor, specification of visual inspection. The visual inspection shall be made in accordance with the "specification of visual inspection before and after sawing process to assure that all chips are free from defects. The quality inspection (final visual inspection) is performed by production

PACKAGE DIMENSIONS in millimeters

Note

⁽¹⁾ Dimension of sawn die under consideration of 30 μm saw kerf



Anode area: 0.23 mm^2

Bonding area: $\text{Ø } 100 \mu\text{m}$

Bonding restricted to this area in order to avoid damage of adjacent structures

Thickness: $280 \mu\text{m} \pm 15 \mu\text{m}$

Drawing-No.: 9.000-5163.01-4

Issue: 1; 28.11.17



HANDLING AND STORAGE CONDITIONS

- The hermetically sealed shipment lots shall be opened in temperature and moisture controlled cleanroom environment only. It is mandatory to follow the rules for disposition of material that can be hazardous for humans and environment
- Product must be handled only at ESD safe workstations. Standard ESD precautions and safe work environments are as defined in MIL-HDBK-263
- Singulated die are not to be handled with tweezers. A vacuum wand with non metallic ESD protected tip should be used

PACKING

Chips are fixed on adhesive foil. Upon request the foils can be mounted on plastic frame or disco frame. For shipment, the wafers are arranged to stacks and hermetically sealed in plastic bags to ensure protection against environmental influence (humidity and contamination).

Use for recycling reliable operators only. We can help getting in touch with your nearest sales office. By agreement we will take back packing material, if it is sorted. You will have to bear the costs of transport. We will invoice you for any costs incurred for packing material that is returned unsorted or which we are not obliged to accept.



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